IN THE CLAIMS:

1-52. (Canceled)

- 53. (Currently amended) A semiconductor thin film formed on an insulating base, comprising[[:]] micro-projections formed on the surface of said semiconductor thin film.
- 54. (Original) A semiconductor thin film according to claim 53, wherein said micro-projections are arranged in an approximately regular pattern.
- 55. (Original) A semiconductor thin film according to claim 53, wherein a height of each of said micro-projections is in a range of 20 nm or less.
- 56. (Original) A semiconductor thin film according to claim 53, wherein a diameter of each of said micro-projections is in a range of 0.1 μm or less.
- 57. (Original) A semiconductor thin film according to claim 53, wherein a radius of curvature of each of said micro-projections is in a range of 60 nm or more.
- 58. (Original) A semiconductor thin film according to claim 53, wherein a density of said micro-projections is in a range of 1 × 1010 pieces/cm2 or less.
- 59. (Original) A semiconductor thin film according to claim 53, wherein a thickness of said semiconductor thin film is in a range of 50 nm or less.
- 60. (Original) A semiconductor thin film according to claim 53, wherein said micro-projections are formed by uplift of boundary portions among polycrystalline grains in said semiconductor thin film.

Aug-03-06

- 61. (Original) A semiconductor thin film according to claim 53, wherein said semiconductor thin film is made of non-single crystals, single crystals, or a combination thereof.
- 62. (Original) A semiconductor thin film according to claim 53, wherein said semiconductor thin film contains a single crystal region having a size of $1 \times 10-8$ cm² or more.
- 63. (Currently amended) A semiconductor thin film according to claim 53, wherein said semiconductor thin film contains a single crystal region having an orientation plane which is either of the (100), (111), and (110) planes.53.

64-125. (Canceled)

126. (Currently amended) A semiconductor thin film <u>according to claim</u>
53, further comprising an said insulating base; and <u>wherein:</u>

said semiconductor thin film comprises a polycrystalline thin film formed in on said insulating base;, in which

said polycrystalline thin film has polycrystalline grains are aligned in an approximately regular pattern; and

wherein <u>said</u> micro-projections are each formed at a boundary position among at least three or more of said polycrystalline grains.

- 127. (Original) A semiconductor thin film according to claim 126, wherein said micro-projections are aligned in an approximately regular pattern.
- 28. (Original) A semiconductor thin film according to claim 126, wherein a thickness of said semiconductor thin film is in a range of 50 nm or less.
- 129. (Original) A semiconductor thin film according to claim 126, wherein a size of each of said polycrystalline grains is in a range of 0.1 μm to 4.0 μm .

From-Sonnenschein Nath & Rosenthal (4) 14:28 314 259 5959 Aug-03-06 T-251 P.005/006 F-541

Attorney Docket No. 09792909-5921

PATENT

130-181. (Canceled)